

a.
This application is a divisional of U.S. Serial No. 09/736,472 filed on December 13, 2000, which is a continuation in part of U.S. Serial No. 09/415,898 filed on October 8, 1999, and of common assignee.

1
2
On page 10, please replace the first full paragraph beginning on line 9 with the following paragraph:

While the preferred embodiment of the invention has been illustrated and described, it will be appreciated that various changes can be made therein without departing from the spirit and scope of the invention. For example, the buff pad may include grooves or slurry holes. Further, the present invention may be applied to other, more primary, processes in which a rotating head is pressed to a circular wafer for the purpose of removing portions of the wafer surface. In this regard, the term "buff" pad and "buffing" as used herein are generically defined to mean a material removing article excluding a primary polish step.

In the Claims

Please cancel claims 1-7, and renumber the remaining claims accordingly.

Remarks

This divisional application is being filed to include the foregoing reference that the present application is a divisional of U.S. Serial No. 09/736,472 filed on December 13, 2000, which is a continuation in part of U.S. Serial No. 09/415,898 filed on October 8, 1999, and of common assignee. This preliminary amendment cancels claims 1-7 of application Serial No. 09/736,472 and renames the remaining claims as claims 1-18 of this application.

Regarding the correction made to the first full paragraph beginning at line 9 of page 10, the word "including" was mistakenly used instead of the intended correct word "excluding". By changing "including" to "excluding" the sentence is made consistent with the following paragraph which begins at line 16 of page 10.